

PATENT ASSIGNMENT

Electronic Version v1.1
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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Atsushi MINAKAWA</td> <td>05/09/2008</td> </tr> <tr> <td>Mamoru SEKIYA</td> <td>05/09/2008</td> </tr> <tr> <td>Norio UMEZU</td> <td>05/09/2008</td> </tr> </tbody> </table>		Name	Execution Date	Atsushi MINAKAWA	05/09/2008	Mamoru SEKIYA	05/09/2008	Norio UMEZU	05/09/2008
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Atsushi MINAKAWA	05/09/2008								
Mamoru SEKIYA	05/09/2008								
Norio UMEZU	05/09/2008								
RECEIVING PARTY DATA									
Name:	ONKYO Corporation								
Street Address:	2-1, Nisshin-cho, Neyagawa-shi								
City:	Osaka								
State/Country:	JAPAN								
Postal Code:	572-8540								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12136117</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12136117				
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Application Number:	12136117								
CORRESPONDENCE DATA									
Fax Number:	(216)621-6165								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
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NAME OF SUBMITTER:	Mark D. Saralino								

Total Attachments: 2
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PATENT
REEL: 021072 FRAME: 0569

OP \$40.00 12136117

ASSIGNMENT

WHEREAS:

NAME(S) AND ADDRESS(ES) OF INVENTOR(S)

Atsushi MINAKAWA
c/o ONKYO Corporation
2-1, Nisshin-cho, Neyagawa-shi
Osaka 572-8540 JAPAN

Mamoru SEKIYA
c/o ONKYO Corporation
2-1, Nisshin-cho, Neyagawa-shi
Osaka 572-8540 JAPAN

Norio UMEZU
c/o ONKYO Corporation
2-1, Nisshin-cho, Neyagawa-shi
Osaka 572-8540 JAPAN

(hereinafter referred to as ASSIGNOR), have invented a certain invention entitled:

TITLE OF INVENTION

SEMICONDUCTOR DEVICE INCLUDING MAIN SUBSTRATE AND SUB SUBSTRATES AND FABRICATION METHOD OF THE SAME

for which application for Letters Patent of the United States has been:

PARTICULARS OF APPLICATION

executed concurrently herewith,
 filed under U.S. Application No. 12/136,117 on 10 JUNE 2008, or
 filed under Express Mail Label No. _____ on _____.

WHEREAS:

NAME, STATE OF INCORPORATION AND ADDRESS OF ASSIGNEE

ONKYO Corporation
2-1, Nisshin-cho, Neyagawa-shi
Osaka 572-8540 JAPAN

(hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire interest in, to and under said invention (including all inventions should said application be deemed to include multiple inventions).

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that in consideration of the payment by ASSIGNEE to ASSIGNOR(S) of the sum corresponding to One Dollar (\$1.00), and for other good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR(S) hereby sells, assigns and transfers to ASSIGNEE the full and exclusive right, title and interest to said invention and all Letters Patent of the United States to be obtained therefor on said application or any continuation, division, renewal, substitute or reissue thereof for the full term or terms for which the same may be granted.

ASSIGNOR hereby covenants that ASSIGNOR has the full power to make this assignment and that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment.

ASSIGNOR further covenants that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent as may be known and accessible to ASSIGNOR and that ASSIGNOR will testify as to the same in any legal proceeding related thereto and will promptly execute and deliver to ASSIGNEE or its legal representative any and all papers, instruments or affidavits required to apply for, obtain, maintain and enforce patent protection for said invention in all countries.

I authorize the patent attorney of record and/or having power of attorney in the U.S. patent application identified above to insert the serial number and filing date information for the patent application in the appropriate spaces in this assignment document when that information becomes available.

FULL NAME(S) OF INVENTORS(S)

Date <u>May, 9, 2008</u>	<u>Atsushi Minakawa</u> Atsushi MINAKAWA
Date <u>May, 9, 2008</u>	<u>Mamoru Sekiya</u> Mamoru SEKIYA
Date <u>May, 9, 2008</u>	<u>Norio Umezumi</u> Norio UMEZU